

	<b>Class</b>	<b>Subclass</b>
<b>ISSUE CLASSIFICATION</b>		

MIT O.I.P.E. PATENT DATE  
 SCANNED KCO Q.A. WJ

APPLICATION NO. 09/996118	CONT/PRIOR	CLASS 257	SUBCLASS 687	ART UNIT 2814	EXAMINER S. RAO
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## APPLICANTS

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**TITLE**

Low resistance metal interconnect lines and a process for fabricating them

PTO-2040  
12/89

ISSUING CLASSIFICATION												
ORIGINAL				CROSS REFERENCE(S)								
CLASS		SUBCLASS		CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)							
INTERNATIONAL CLASSIFICATION												

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<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>	<b>DRAWINGS</b>			<b>CLAIMS ALLOWED</b>	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner) (Date)			<b>NOTICE OF ALLOWANCE MAILED</b>	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____ _____	_____ (Primary Examiner) (Date)			<b>ISSUE FEE</b>	
				Amount Due	Date Paid
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	_____ (Local Instruments Examiner) (Date)			<b>ISSUE BATCH NUMBER</b>	

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